



SOT1570-3

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.50 mm pitch; 14 mm x 14 mm x 1.4 mm body

12 April 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package type industry code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-3-2018
Manufacturer package code	98ASA01176D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	14	-	mm
E	package width	-	-	14	-	mm
A	seated height	-	-	1.4	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	100	-	A/A



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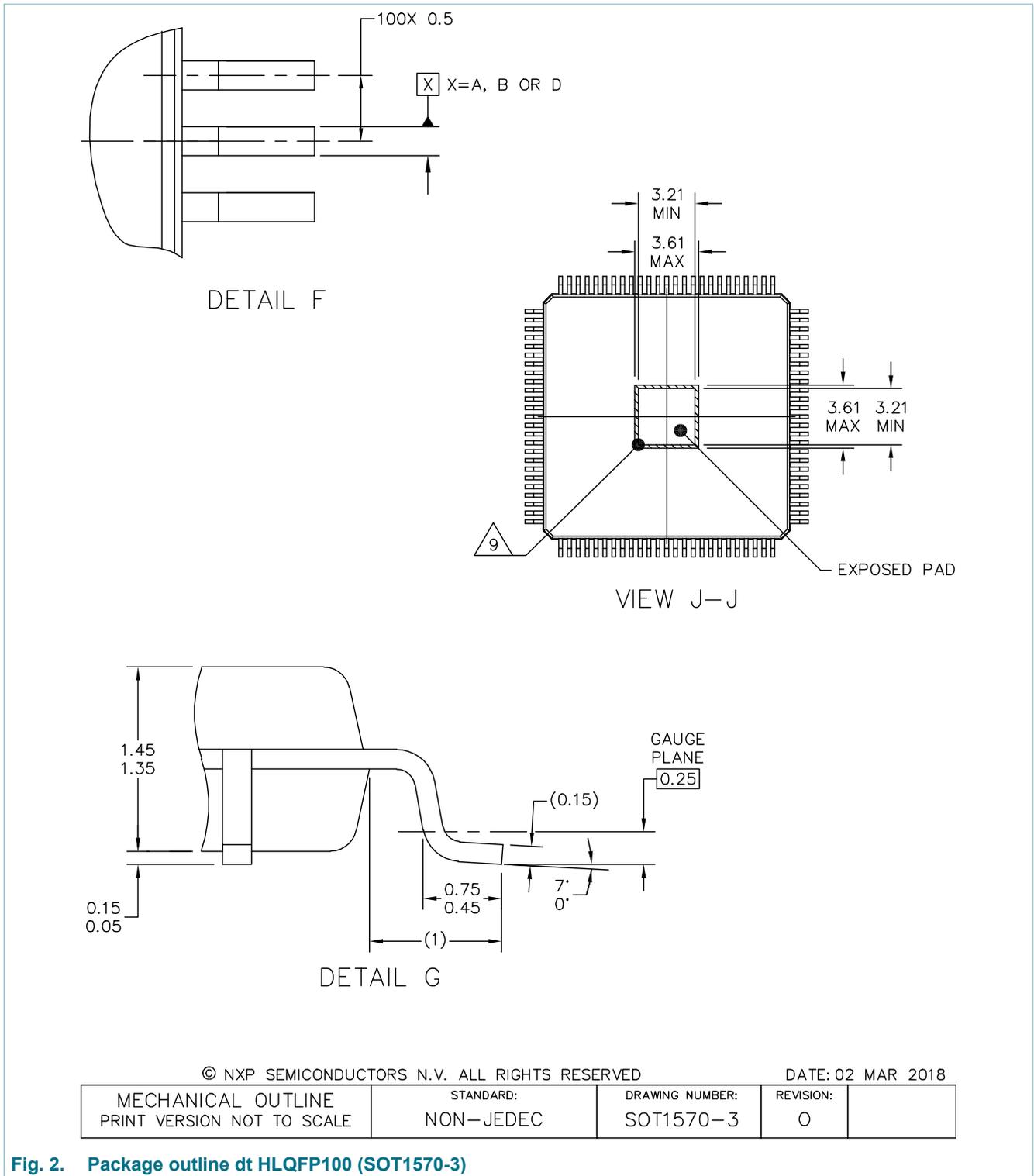


Fig. 2. Package outline dt HLQFP100 (SOT1570-3)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 02 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: SOT1570-3	REVISION: 0	
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Fig. 3. Package outline note HLQFP100 (SOT1570-3)

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3. Soldering

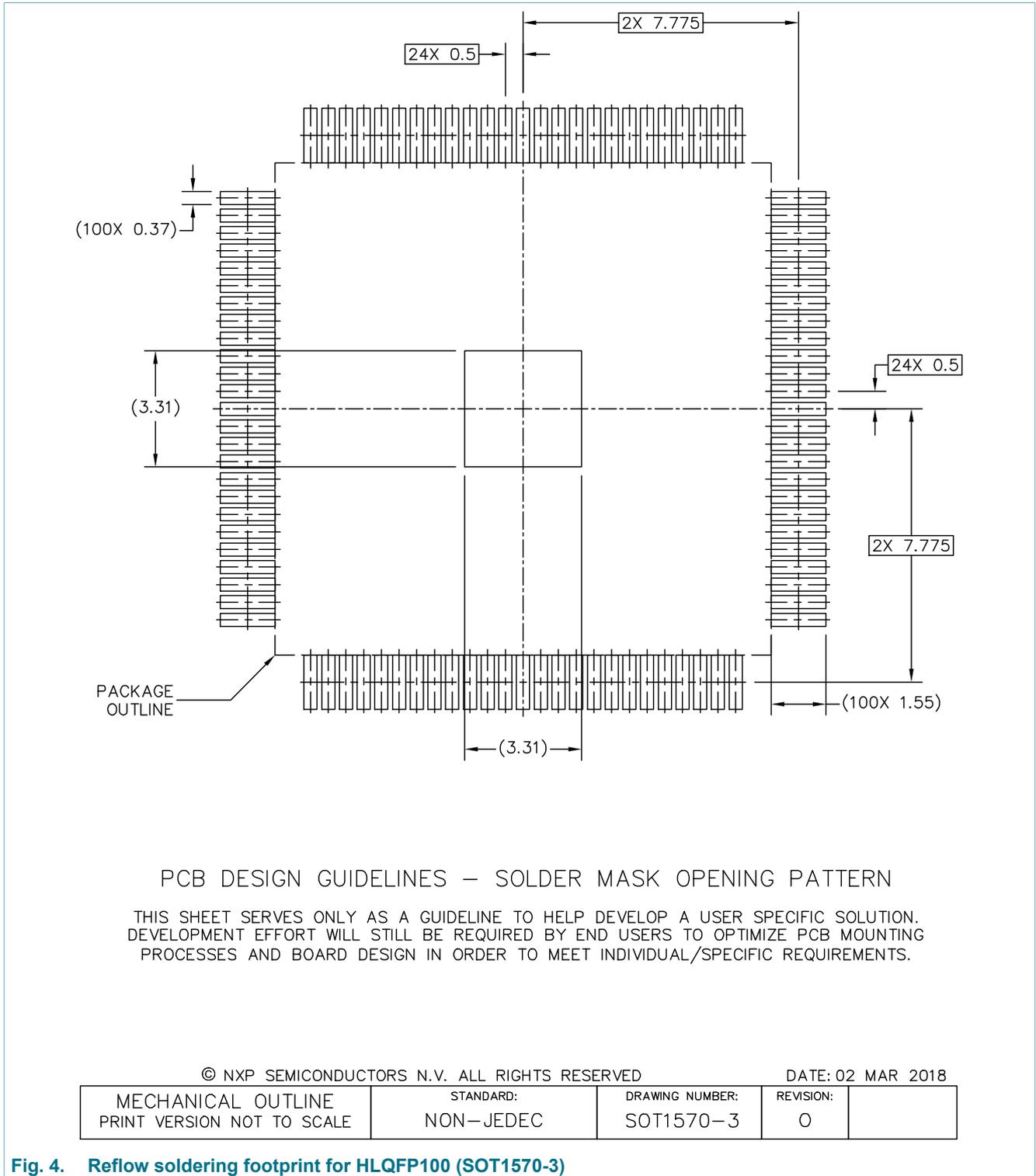
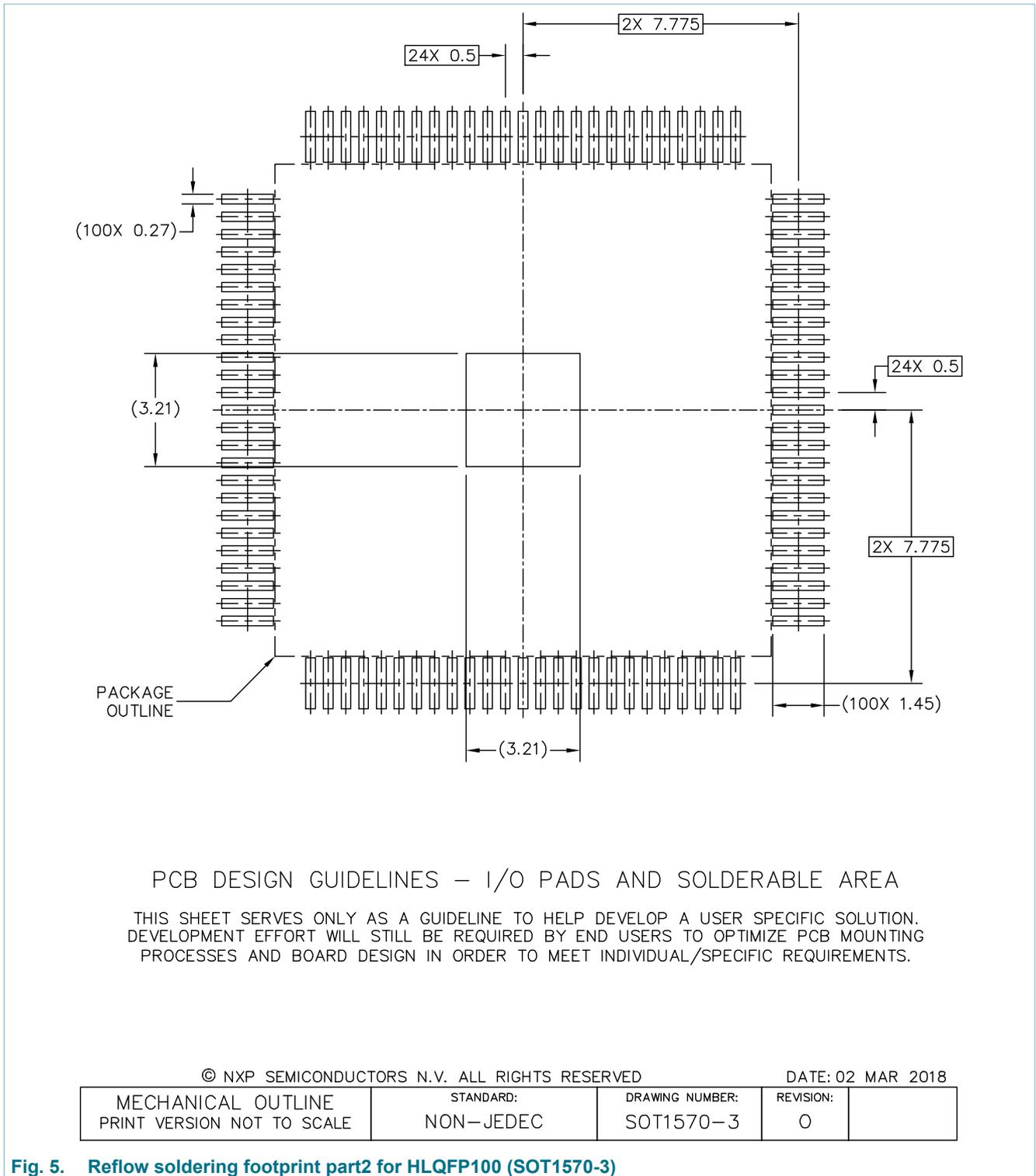


Fig. 4. Reflow soldering footprint for HLQFP100 (SOT1570-3)

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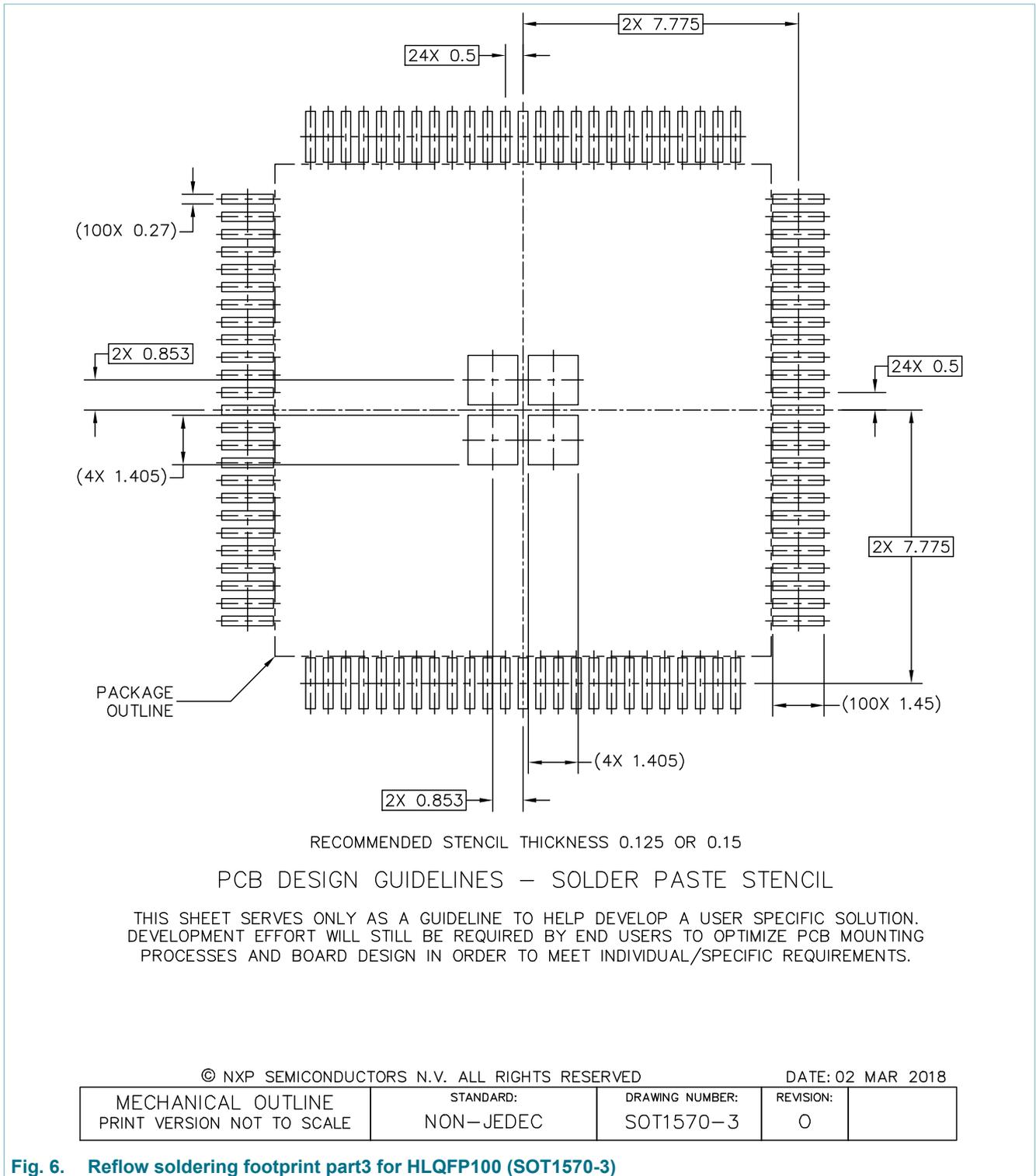


Fig. 6. Reflow soldering footprint part3 for HLQFP100 (SOT1570-3)

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4. Legal information

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